

4226020/B 12/2020

NOTES:

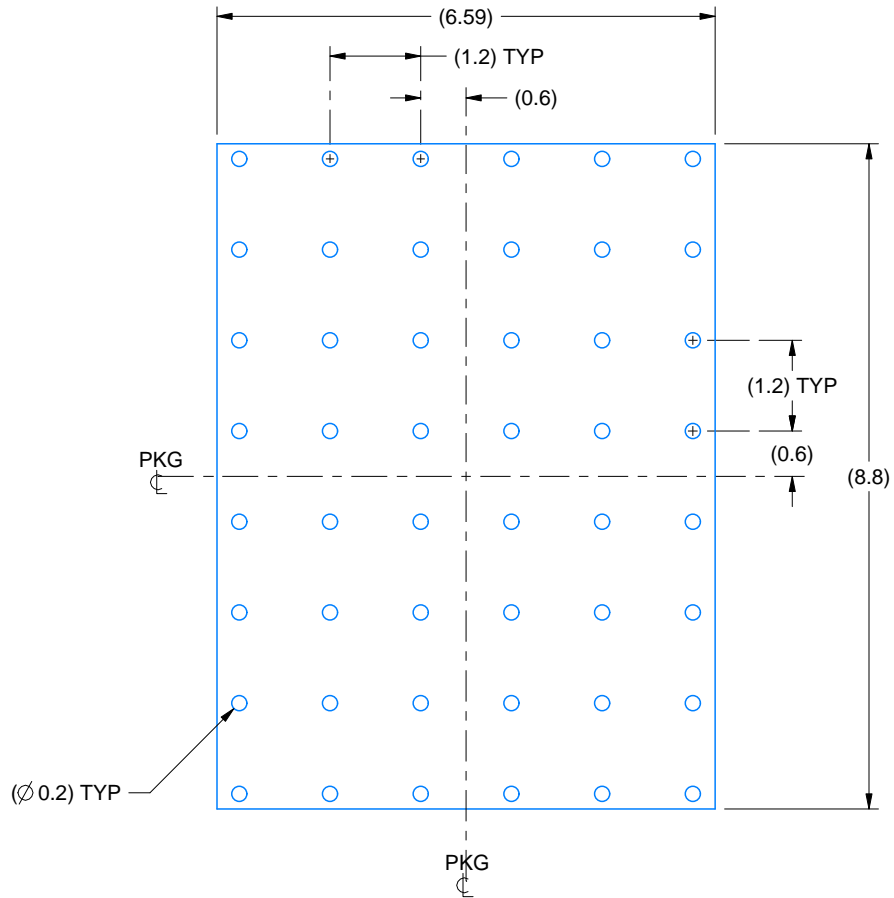
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid. Lid is connected to Heatsink and pin 8 (GND).
4. The terminals are gold plated.
5. Falls within MIL-STD-1835 CDFP-F11A.

# EXAMPLE BOARD LAYOUT

HKR0016A

CFP - 2.416 mm max height

CERAMIC DUAL FLATPACK



**HEATSINK LAND PATTERN EXAMPLE**  
EXPOSED METAL SHOWN  
SCALE:10X

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